L Number	Hits	Search Text	DB	Time stamp
1	1	(semiconductor or semiconductive) and (organic with (insulat$4 or dielectric)) and ethyne and (UV same (heat or heating or heated or anneal or annealing or annealed or bake or baking or baked))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/20 11:40
2	24	(semiconductor or semiconductive) and (organic with (insulat$4 or dielectric)) and SILK and (UV same (heat or heating or heated or anneal or annealing or annealed or bake or baking or baked))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/20 11:41
3	3	(semiconductor or semiconductive) and (organic with (insulat$4 or dielectric)) and SILK and (UV same (heat or heating or heated or anneal or annealing or annealed or bake or baking or baked) same polymeriz$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/20 11:46
4	64	(semiconductor or semiconductive) and (organic with (insulat$4 or dielectric)) and (UV same (heat or heating or heated or anneal or annealing or annealed or bake or baking or baked) same polymeriz$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/20 13:10
5	45	((semiconductor or semiconductive) and (organic with (insulat$4 or dielectric)) and (UV same (heat or heating or heated or anneal or annealing or annealed or bake or baking or baked) same polymeriz$5)) and (monomer or oligomer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/20 11:47
6	6	((thin adj film) or TFT) and (organic with (insulat$4 or dielectric)) and (UV same (heat or heating or heated or anneal or annealing or annealed or bake or baking or baked) same polymeriz$5) and (SILK or "GX-3")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/20 13:09
7	9	(organic with (insulat$4 or dielectric)) and (UV same (heat or heating or heated or anneal or annealing or annealed or bake or baking or baked) same polymeriz$5) and (SILK or "GX-3")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/20 13:10
8	3	((organic with (insulat$4 or dielectric)) and (UV same (heat or heating or heated or anneal or annealing or annealed or bake or baking or baked) same polymeriz$5) and (SILK or "GX-3")) not (((thin adj film) or TFT) and (organic with (insulat$4 or dielectric)) and (UV same (heat or heating or heated or anneal or annealing or annealed or bake or baking or baked) same polymeriz$5) and (SILK or "GX-3"))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/20 13:09
9	62	(organic with (insulat$4 or dielectric)) and (UV and (heat or heating or heated or anneal or annealing or annealed or bake or baking or baked) and polymeriz$5) and (SILK or "GX-3")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/20 13:12
10	24	((organic with (insulat$4 or dielectric)) and (UV and (heat or heating or heated or anneal or annealing or annealed or bake or baking or baked) and polymeriz$5) and (SILK or "GX-3")) not (silk adj screen$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/20 13:19
11	2510	((438/758) or (438/780-781) or (438/789-790)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/20 16:09
12	53	(((438/758) or (438/780-781) or (438/789-790)).CCLS.) and (SILK or "GX-3")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/20 13:25

13	2	((((438/758) or (438/780-781) or (438/789-790)).CCLS.) and (SILK or "GX-3")) and ((UV or ultraviolet) with polymeriz$6)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/20 13:26
14	8	(((438/758) or (438/780-781) or (438/789-790)).CCLS.) and (organic with (insulat$4 or dielectric)) and ((UV or ultraviolet) with polymeriz$6)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/20 14:37
15	42	(UV or ultraviolet) with (heat or heating or cure or curing or anneal or annealing or bake or baking) with polymer$8 with (low adj temperature)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/20 14:38
16	0	((UV or ultraviolet) with (heat or heating or cure or curing or anneal or annealing or bake or baking) with polymer$8 with (low adj temperature)) and (SILK) not (silk adj screen$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/20 14:39
17	0	((UV or ultraviolet) with (heat or heating or cure or curing or anneal or annealing or bake or baking) with polymer$8 with (low adj temperature)) and (organic with (insultati$4 or dielectric))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/20 14:39
18	2	((UV or ultraviolet) with (heat or heating or cure or curing or anneal or annealing or bake or baking) with polymer$8 with (low adj temperature)) and (organic with precursor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/20 15:06
19	6548	(438/149-166).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/20 15:07
20	41	((438/149-166).CCLS.) and (transparent with substrate) and matrix.ti. and (gate with line) and electrode$1 and (source with line) and (source with electrode$1) and (pixel with electrodes)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/20 15:09
21	9	(((438/149-166).CCLS.) and (transparent with substrate) and matrix.ti. and (gate with line) and electrode$1 and (source with line) and (source with electrode$1) and (pixel with electrodes)) and (organic with (dielectric or insulati$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/20 15:09
22	2	("4756977").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/20 16:10